



Refining & Chemicals
Polymers

TPSeal® PP 20C1

Technical Data Sheet
Specialty Compounds
Polypropylene Rotational Moulding
Produced in Europe

Description

TPSeal® PP 20C1 is a metallocene random copolymer Polypropylene (mPP) Compound.

TPSeal® PP 20C1 is intended for the manufacture of rotomoulded items and available in natural, in pellets or in powder.

Main Characteristics

Its specific molecular structure ensures:

- ✓ Low warpage, low shrinkage
- ✓ High gloss
- ✓ Good optical design properties
- ✓ Improved impact properties

Application

Structural parts, design (furniture), house appliances, ...

Properties

Property	Method	Unit	Typical value (*)
Melt Flow Rate (230°C-2.16kg)	ISO 1133/D	g/10min	20.0
Melting Temperature	ISO 11357	°C	138
Vicat Softening Point (Method A50)	ISO 306	°C	114
Heat Deflection Temperature (Method B)	ISO 75	°C	71
Tensile modulus	ISO 527	MPa	800
Tensile strength @yield	ISO 527	MPa	20

(*) Data not intended for specification purposes

Processing conditions

It is recommended to keep product dry prior use for production.

Handling and storage

Please refer to the material safety data sheet (MSDS) for handling and storage information. It is advisable to convert the product within one year after delivery provided storage conditions are used as given in the MSDS of our product.

MSDS may be obtained from the website: <http://www.polymers.total.com/>

Specialty Compound

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